Specification of Thermoelectric Module

TEC3-127-71-31-06

Description

The TEC3-127-71-31-06 is a multistage module designed for greater temperature differential cooling, good for cooling and heating up to 100 °C applications. It is a 127-71-31 couples module in size of 20mm×20mm (top)/40mm ×40mm (bottom). If higher operation or processing temperature is required, please specify, we can design and manufacture according to your special requirements.

Features

- High Temperature Differential
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- **RoHS** compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

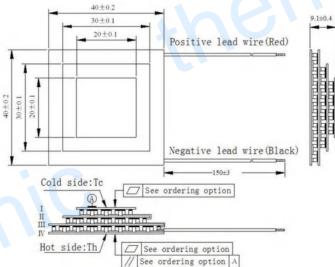
Performance Specification Sheet

Application

- Infrared (IR) Sensors
- CCD Sensor
- Gas Analyzers
- Calibration Equipment
- CPU cooler and scientific instrument
- Photonic and medical systems
- Guidance Systems

`			1	
Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C)	102	114	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	14.6	16.4	Voltage applied to the module at DT _{max}	
I _{max} (Amps)	5.0	5.0	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	18.1	19.9	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	2.8	3.01	The module resistance is tested under AC	
Tolerance	10%		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

A. Solder:

- 1. T100: BiSn (Tmelt=138°C)
- 2. T200: CuAgSn (Tmelt = 217°C)
- 3. T240: SbSn (Tmelt = 240°C)
- C. Ceramics:
- 1. Alumina (Al₂O₃, white 96%)
- 2. Aluminum Nitride (AlN)

- **B. Sealant:**
- 1. NS: No sealing (Standard)
- 2. SS: Silicone sealant
 - 3. EPS: Epoxy sealant
 - **D. Ceramics Surface Options:**
 - 1. Blank ceramics (not metalized)
 - 2. Metalized

Ordering Option

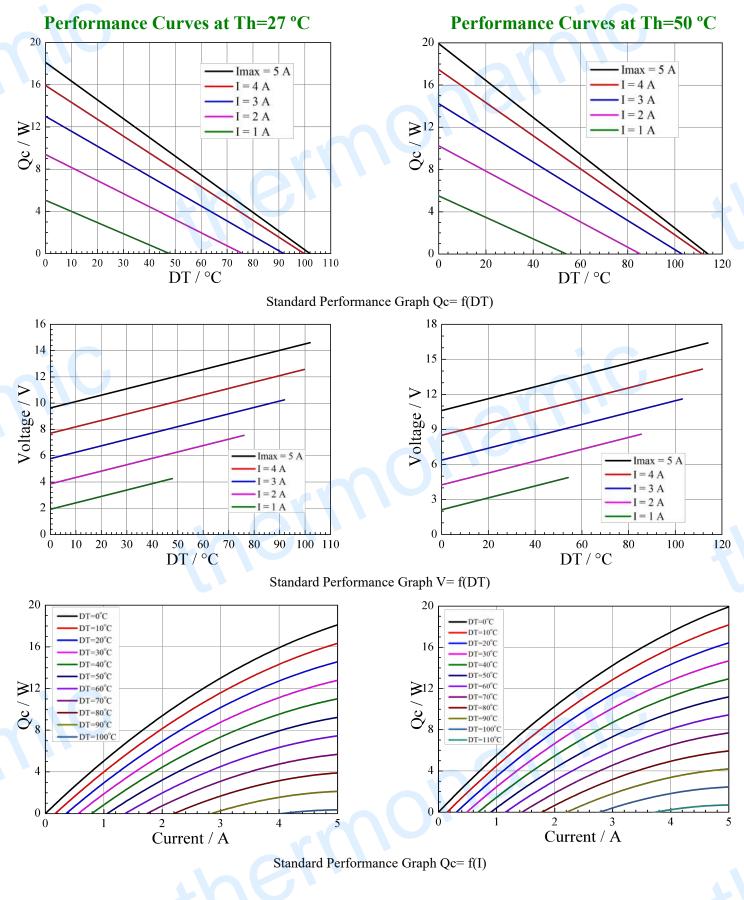
Naming for the Module

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length	TEC3-127-71-31-06- X-X-X-X Ceramics Flatness/ Parallelism
TF	0: 9.2± 0.3	0: 0.08/0.08	150±3/Specify	Sealant Solder
TF	1: 9.2± 0.15	0.15 1: 0.03/0.03 150±3/Specify		TEC3-127-71-31-06-T100 -NS -TF01 -AIO
Eg. TF01: Thickness 9.2±0.3 (mm) and Flatness/ Parallelism 0.03/0.03 (mm)			ss/ Parallelism 0.03/0.03 (mm)	T100: BiSn(Tmelt=138*C) NS: No sealing AlO: Alumina white 96%

Creative technology with fine manufacturing processes provides you the reliable and quality products Tel: +86-791-88198288 Fax: +86-791-88198308 Email: sales@thermonamic.com.cn Web Site: www.thermonamic.com.cn

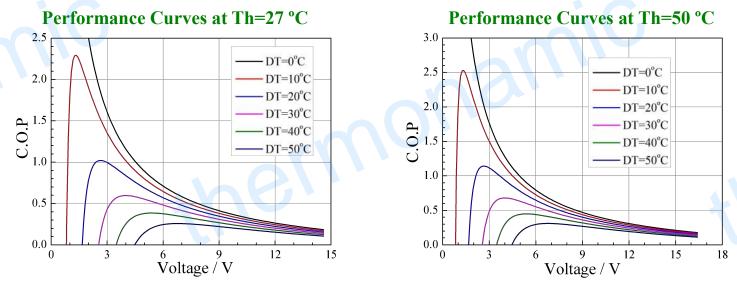
Specification of Thermoelectric Module

TEC3-127-71-31-06

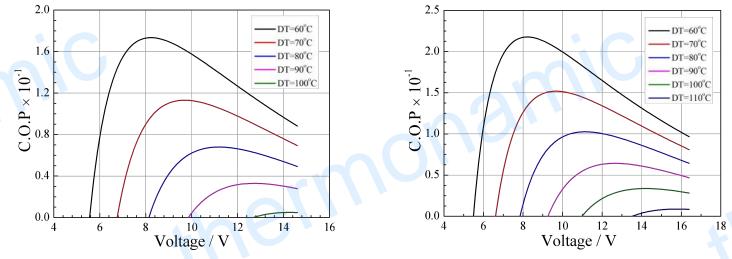


Specification of Thermoelectric Module

TEC3-127-71-31-06



Standard Performance Graph COP = f(V) of DT ranged from 0 to 50 °C



Standard Performance Graph COP = f(V) of DT ranged from 60 to 100/110 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power ($V \times I$).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Susur • Attach the hot side of module to a heat radiator for heat dissipating
- Operation or storage module below 100 °C
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.